Title (en)

LOW TEMPERATURE METHOD AND COMPOSITIONS FOR PRODUCING ELECTRICAL CONDUCTORS

Title (de)

NIEDERTEMPERATURVERFAHREN UND ZUSAMMENSETZUNGEN ZUR HERSTELLUNG ELEKTISCHER LEITER

Title (fr)

PROCEDE ET COMPOSITIONS A BASSE TEMPERATURE POUR LA PRODUCTION DE CONDUCTEURS ELECTRIQUES

Publication

EP 0961809 B1 20070207 (EN)

Application

EP 97941061 A 19970912

Priority

- US 9716226 W 19970912
- US 3866997 P 19970220
- US 3851497 P 19970220
- US 3867097 P 19970220
- US 3845397 P 19970220
- US 4655297 P 19970515
- US 4654197 P 19970515
- US 4654097 P 19970515

Abstract (en)

[origin: WO9837133A1] A composition for matter having a metal powder or powders for specified characteristics in a Reactive Organic Medium (ROM). These compositions can be applied by any convenient printing process to produce patterns of electrical conductors on temperature-sensitive electronic substrates. The patterns can be thermally cured in seconds to form pure metal conductors at a temperature low enough to avoid damaging the substrate.

IPC 8 full level

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CPC (source: EP KR)

C08K 3/08 (2013.01 - EP KR); **H01B 1/22** (2013.01 - EP); **H01L 21/288** (2013.01 - EP); **H01L 21/4867** (2013.01 - EP); **H01L 21/76838** (2013.01 - EP); **H01L 23/49883** (2013.01 - EP); **H05K 1/097** (2013.01 - EP); H01L 24/03 (2013.01 - EP); H01L 24/05 (2013.01 - EP); H01L 24/11 (2013.01 - EP); H01L 2224/05124 (2013.01 - EP); H01L 2224/05639 (2013.01 - EP); H01L 2224/05644 (2013.01 - EP); H01L 2224/05647 (2013.01 - EP); H01L 2224/05655 (2013.01 - EP); H01L 2224/05666 (2013.01 - EP); H01L 2224/05684 (2013.01 - EP); H01L 2224/13099 (2013.01 - EP); H01L 2224/45144 (2013.01 - EP); H01L 2924/01005 (2013.01 - EP); H01L 2924/01006 (2013.01 - EP); H01L 2924/01013 (2013.01 - EP); H01L 2924/01015 (2013.01 - EP); H01L 2924/01016 (2013.01 - EP); H01L 2924/01019 (2013.01 - EP); H01L 2924/0102 (2013.01 - EP); H01L 2924/01022 (2013.01 - EP); H01L 2924/01023 (2013.01 - EP); H01L 2924/01027 (2013.01 - EP); H01L 2924/01029 (2013.01 - EP); H01L 2924/0103 (2013.01 - EP); H01L 2924/01033 (2013.01 - EP); H01L 2924/01039 (2013.01 - EP); H01L 2924/01042 (2013.01 - EP); H01L 2924/01044 (2013.01 - EP); H01L 2924/01045 (2013.01 - EP); H01L 2924/01046 (2013.01 - EP); H01L 2924/01047 (2013.01 - EP); H01L 2924/01049 (2013.01 - EP); H01L 2924/01051 (2013.01 - EP); H01L 2924/01057 (2013.01 - EP); H01L 2924/01074 (2013.01 - EP); H01L 2924/01076 (2013.01 - EP); H01L 2924/01077 (2013.01 - EP); H01L 2924/01078 (2013.01 - EP); H01L 2924/01079 (2013.01 - EP); H01L 2924/01082 (2013.01 - EP); H01L 2924/01087 (2013.01 - EP); H01L 2924/014 (2013.01 - EP); H01L 2924/09701 (2013.01 - EP); H01L 2924/12044 (2013.01 - EP); H01L 2924/14 (2013.01 - EP); H01L 2924/15787 (2013.01 - EP); H01L 2924/19043 (2013.01 - EP); H01L 2924/3025 (2013.01 - EP)

C-Set (source: EP)

1. H01L 2924/15787 + H01L 2924/00
2. H01L 2924/12044 + H01L 2924/00
3. H01L 2224/45144 + H01L 2924/00
4. H01L 2224/05639 + H01L 2924/00014
5. H01L 2224/05644 + H01L 2924/00014
6. H01L 2224/05647 + H01L 2924/00014
7. H01L 2224/05655 + H01L 2924/00014
8. H01L 2224/05666 + H01L 2924/00014
9. H01L 2224/05684 + H01L 2924/00014
10. H01L 2224/05124 + H01L 2924/00014

Cited by

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